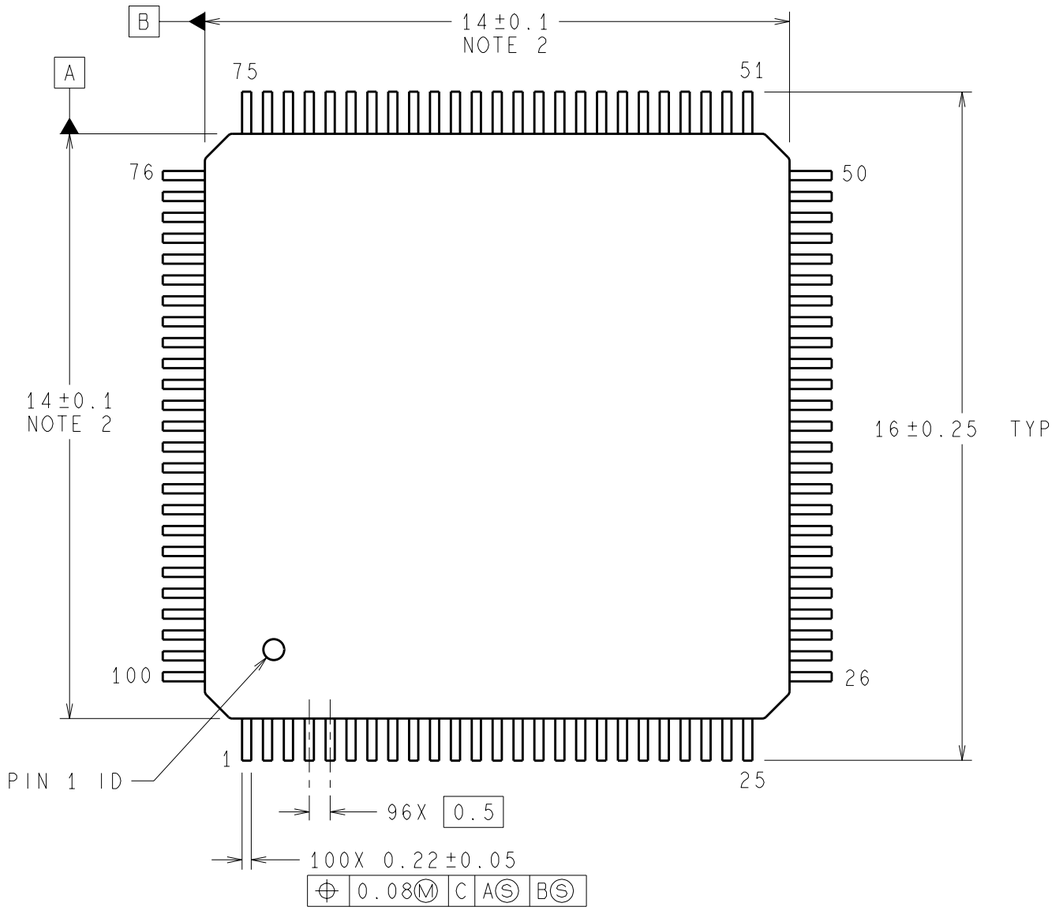
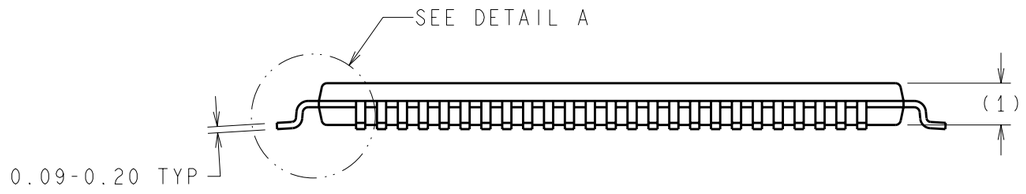
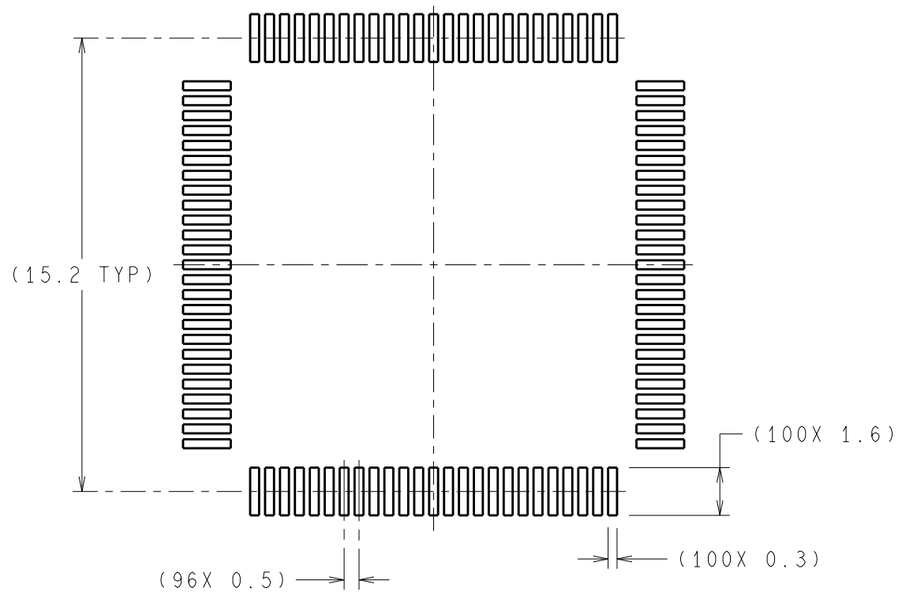
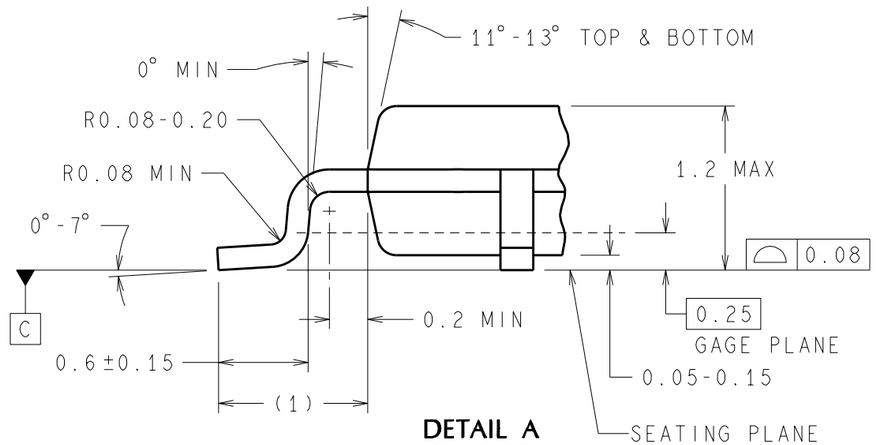
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10712	11/22/1994	DEG/HJK
B	TITLE:TQFP WAS PQFP; UPDATE NOTE 3; ADD GEOMETRC TOLERANCE	12317	12/02/1999	ACS/MS/RW
C	REV NOTE 1; ADD LAND PATTERN; CHG DWG FORMAT TO B SIZE; BODY THICKNESS: (1) WAS 1+/-0.05	1263	05/11/2004	TL/RW







RECOMMENDED LAND PATTERN



DETAIL A
SCALE:25X

NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
3. REFERENCE JEDEC REGISTRATION MS-026,VARIATION AED.

DIMENSIONS ARE IN MILLIMETERS
DIMENSION IN ( ) FOR REFERENCE ONLY

APPROVALS	DATE
DRAWN D.E Grady	11/22/1994
DFTG. CHK. MARTA SUCHY	05/11/2004
ENGR. CHK. RANDALL WALBERG	05/11/2004

National Semiconductor
2900 Semiconductor Dr., Santa Clara, CA 95052-8090

TQFP, JEDEC METRIC,
14 X 14 X 1.0mm,
100 LEAD

PROJECTION MM

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-VJD100A	C

FORMERLY: N/A

SHEET 1 of 1